Materials Declaration

Package	BGA_ED
Body Size	40 X 40
Ball Count	432
Option	Sn/Pb
Ball Size	0.76 mm

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	73.2	2.04 E-01	22074
Resin	26.8	7.50 E-02	8116
Subtotal		2.79 E-01	30190

Dam

Item	% of Dam	Weight (g)	PPM
SiO2 Filler	73.0	7.15 E-03	774
Resin	27.0	2.65 E-03	286
Subtotal		9.80 E-03	1060

Laminate

Item	% of Laminate	Weight (g)	PPM
BT	61.10	5.12 E-01	55402
Solder Mask	22.08	1.85 E-01	20018
Copper	15.51	1.30 E-01	14067
Nickel	0.95	8.00 E-03	866
Gold	0.24	2.00 E-03	216
Brominated compound	0.12	1.00 E-03	108
Subtotal		8.38 E-01	90678

Solder Ball

	% of Solder Ball	Weight (g)	PPM
Sn	63.0	5.55 E-01	60055
Pb	37.0	3.26 E-01	35276
Subtotal		8.81 E-01	95331

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.91 E-02	2067

Chip

	% of Chip	Weight (g)	PPM
Si	100.0	8.34 E-02	9025

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	75.0	7.00 E-03	757
Resin	25.0	2.00 E-03	216
		9.00 E-03	974

Heat Sink

	% of Heat Sink	Weight (g)	PPM
Cu		6.83 E+00	739079

Heat Sink Plating

	% of Heat Sink Plating	Weight (g)	PPM
Ni	100.0	2.92 E-01	31597

Molding Compound

Item	PPM	Method
Pb		
Cd		
Hg		
Cr+6		
PBB		
PBDE		

Die Attach

Item	PPM	Method
Pb	<5 PPM	ICP-MS
Cd	<5 PPM	ICP-MS
Hg	<5 PPM	ICP-MS
Cr+6	< 0.5 PPM	Absorptiometer
PBB	None Detected	Analysis was performed by GC/MS
PBDE	None Detected	Analysis was performed by GC/MS

Laminate

Item	PPM	Method
Pb		
Cd		
Hg		
Cr+6		
PBB		
PBDE		

Package Totals

Weight (g)	PPM
9.24 E+00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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